

Module Status January 2019







- \triangleright Modules left
 - → Tested L2-bwd (OB): 15
 - → Tested L2-fwd (OF): 12
 - \mapsto Modules still to be tested, all passed already the probe card test
 - → at MPP: W04_OB1, W10_OB1, W02_OF1
 - → at GOE: W05_OF1
 - → at BN: W45_OF2 (seems to have JTAG issues, under investigation)
 - → at HLL: W04_OF1 (GOE: high currents, under investigation)
- \triangleright Sensors left from the current production
 - → B-grade sensors: 1 L1-fwd, 6 L2-fwd, 1 L2-bwd, 2 L1-bwd

 \rightarrow ready for assembly

 \rightarrow With possible matrix shorts: 2 L1-fwd, 4 L2-fwd, 0 L2-bwd, 1 L1-bwd \rightarrow tbc

	IF	OF	OB	IB	total
Final modules	15	22	20	14	71
final-P2 modules	2	2	2	2	8
Prototype modules	2	3	5	4	14
EMCM assemblies	3	3	3	3	12
used dummies (mostly ladder)	7	10	9	7	33
stock - not usable	5	24	30	3	62
stock - b-grade	1(+2)	6(+4)	1(+0)	2(+1)	10(+6)

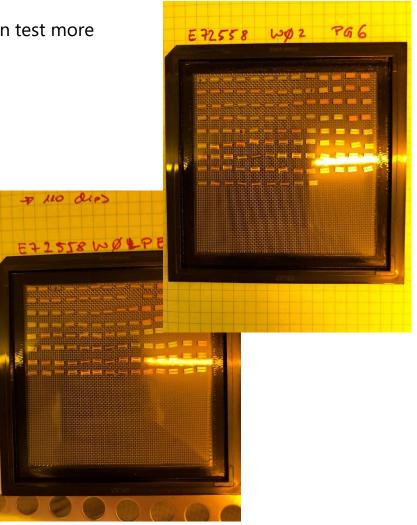




- ▷ DHPT1.2b (Bonn)
 - → Need ~100 ASICs for L1 including 50% spares
 - \rightarrow Currently available at Bonn: 252 tested and 300 untested \rightarrow 2x safety, if needed can test more

▷ DCDB4.2 (KIT)

- → Need ~100 ASICs for L1 including 50% spares
- → Available at KIT: 800 **untested** chips
- \mapsto KIT agreed to test the required number of chips, not critical
- \triangleright No SwitcherB18v2.1 left \rightarrow SwitcherB18v2.2
 - → Slightly improved version of the currently used SwitcherB18v2.1
 - \mapsto Reduced power in V_{sub} node
 - \rightarrow Clamp circuit added between V_{dd} and GND and between V_{ddRef} and V_{SUB}
 - → Changes in termination to allow default operation without JTAG
 - \rightarrow 4 wafers with about 400 chips in total available
 - → Bumping on wafer level at IZM
 - → 2 wafers already bumped and cutand (~200) chips are at HLL

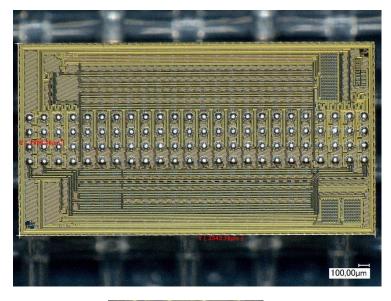


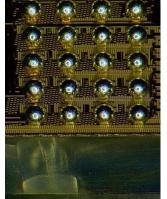


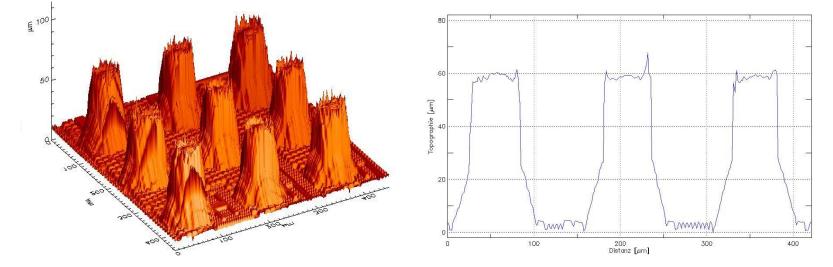
SwitcherB18v2.2



\triangleright ~100 chips for EDET, ~100 chips for PXD \rightarrow very nice bumps!







 \triangleright Flip-chip ~5 untested chips to adapters, test on hybrid level at HLL, BN(?)

 $Descript{S}$ All other chips for series testing on probe station to KIT





- ▷ Check L1 sensors with DS shorts on probe station, make them usable ...
 - → W06-IF (98.8%): 6 DS shorts
 - → W11-IB (98.7%): 2 DS shorts, "repaired"
 - → W11-IF (99.3%): 6 DS shorts, "repaired"
- ▷ W05-IB (98.4%), W06-IB (99.5%), W10-IF (99.0%)
- ▷ W13-OB2 (98.4%), W12-OF2 (98.9%)
- > As soon as first tested SWBs (and DCDs, DHPTs already tested okay): assemble 3 L1 pairs, 1 L2 pair
 - $\rightarrow \quad \text{Place new order to } \text{IZM} \rightarrow \text{MPP?}$
- \triangleright What else?
 - → Kapton cables? How many are available? **Need to order more ... → MPP?**
 - \rightarrow Jigs? Please send all your module jigs to HLL, we will clean them ...
 - \mapsto Need to revive module probe card setup
 - \mapsto Restart test setups for modules ..



Ladder inventory and Rework



\triangleright 2 L1 ladders at DESY

- \rightarrow One with broken EOS \rightarrow backup
- \rightarrow One with possibly broken Switcher L1-035 \rightarrow rework!
 - └→ Rework, also on ladder level, now possible at HLL
- ▷ 1 spare L1 ladder at KEK: L1-037
- $\,\triangleright\,$ Even without PXD9-20 and -21 \rightarrow 1/2 of PXD2020 L1 in reach
 - \mapsto We have one L1 ladders in hand and if we repair L1-035 one more
 - → Modules for three more L1 ladders are being prepared in the next months

